

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Sang-Soo PARK	12/15/2009
Seung-In SHIN	12/15/2009
RECEIVING PARTY DATA	
Name:	Hynix Semiconductor, Inc.
Street Address:	San 136-1, Ami-ri, Bubal-eup, Icheon-si
City:	Gyeonggi-do
State/Country:	REPUBLIC OF KOREA
Postal Code:	467-701
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12640812
CORRESPONDENCE DATA	
Fax Number: (571)327-5452 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 571-327-5450 Email: jbak@ipntlaw.com Correspondent Name: IP & T Law Firm PLC Address Line 1: 7700 Little River Turnpike Address Line 2: Suite 207 Address Line 4: Fairfax, VIRGINIA 22003	
ATTORNEY DOCKET NUMBER:	P09H0221/US
NAME OF SUBMITTER:	Jung H. Kim
Total Attachments: 1 source=P09H0221US-Assignment#page1.tif	

OP \$40.00 12640812

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PATENT
REEL: 023670 FRAME: 0924

ASSIGNMENT OF PATENT APPLICATION

WHEREAS I/We, the below named inventor(s) has made an invention entitled:

METHOD FOR FABRICATING SEMICONDUCTOR DEVICE

For which I/We executed an application for Letters Patent of the United States concurrently herewith; and/or
For which I/We filed an application for Letters Patent of the United States on December 17, 2009 (Application No. 12/640,812),

BE IT KNOWN that, for good and valuable consideration, the receipt of which is hereby acknowledged, I/We, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto **Hynix Semiconductor, Inc.**, a corporation of the Republic of Korea, whose post office address is **San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Republic of Korea** (hereinafter referred to as Assignee), its lawful successors and assigns my/our entire right, title, and interest in and to this application and the invention(s) and improvement(s) set forth therein; and any and all continuations, continuations-in-part, divisionals, and renewals of and substitutes for said application for said Letters Patent and any and all Letters Patent of the United States and of countries foreign thereto, which may be granted thereon or therefore; and any reissues, reexaminations, or extensions of all such Letters Patent.

I/WE HEREBY authorize the Assignee, its lawful successors and assigns to apply for Letters Patent in all countries foreign to the United States directly in its own name, and to claim priority of the filing date of any of the above-mentioned applications for Letters Patent of the United States and of countries foreign thereto under the provisions of any and all international conventions and treaties.

I/WE HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States and official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as fore said, to issue all Letters Patent for this invention to the Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with said Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid said Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and in countries foreign thereto, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys of record to insert the serial number and filing date of said application now identified by the attorney docket number and title set forth above as soon as the same shall have been known to them by the United States Patent and Trademark Office.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Signature of first assignor:

Name of first assignor:

Address:

SS Park
PARK, Sang-Soo

San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Republic of Korea

Date December 15, 2009

Signature of second assignor:

Name of second assignor:

Address:

SHIN
SHIN, Seung-In

San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Republic of Korea

Date December 15, 2009